Amendments to the Specification:

Please replace the paragraph beginning on page 3, line 16, with the following amended paragraph:

The layer thickness of the dielectric layer \underline{d}_{medium} having the dielectric constant ϵ_{medium} should preferably be selected such that

$$\frac{\varepsilon_{\text{medium}} \cdot d_{\varepsilon}}{\varepsilon \cdot d_{\text{medium}}} > 5$$

so that the metallization structure that is next in the vertical direction is well decoupled. In respect of the decoupling in the horizontal direction, the following should apply

$$\frac{\varepsilon_{\text{medium}} \cdot d_{\text{min}}}{d_{\text{medium}} \cdot \varepsilon} > 7$$

where d_{min} is the minimum distance to the next metallization structure in the plane.

Please replace the paragraph beginning on page 5, line 4, with the following amended paragraph:

Fig. 3 shows the three-dimensional (<u>i.e.</u>, <u>X</u>, <u>Y</u>, <u>Z</u> directions) design of the series resonant circuit structure 20 with the capacitor electrode 22, the line 24, and supply lines 26. <u>As shown in Fig. 3, the capacitor electrode 22 and the The-supply lines 26 connect to the line 24.</u>